

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	30	702/117.ccls. and temperature same (integrated near circuit (ic) wafer semiconductor) and resistors! and conduct\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/27 17:06
L2	1	702/117.ccls. and temperature same (integrated near circuit (ic) wafer semiconductor) and resistors! and conduct\$3 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/27 17:08
L3	15	324/760.ccls. and temperature same (integrated near circuit (ic) wafer semiconductor) and resistors! and conduct\$3 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/27 17:08
L4	5	324/760.ccls. and temperature same (integrated near circuit (ic) wafer semiconductor) and resistors! and heat with conduct\$3 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/27 17:08
L5	15	(temperature same (integrated near circuit (ic) wafer semiconductor) and resistors! and conduct\$3 and package).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/27 17:10